



INTEL VALIDATED DDR4 3200 RDIMMS

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DDR4 RDIMM System-Level Validation Results on 3rd Gen Intel Xeon Scalable Processors listed below are the results from a small sample of DDR4 RDIMMS tested on Intel® Xeon® Scalable Processors on the Whitley and Cedar Island Platforms. We are providing this information as a guide to module compatibility with Intel Server reference platforms. This testing is not intended to replace the normal OEM qualification process. All parts used are recommended to be run with the latest Intel® platform Reference Code Production Version.

| DDR4 RDIMM tested in the following conditions: 3200 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channels 2933 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channel | | | | | | | | | | | |
|---|------------------|------|----|----------|---------------|-------------------|-------------|-------|-----------|-----------------|--------------|
| DIMM | | | | DRAM | | | | | | Register | |
| DIMM Supplier | DIMM Part Number | Size | CL | Raw Card | DRAM Supplier | DRAM Part Number | Die Density | Width | Date Code | Register Vendor | Register Rev |
| Kingston | KSM32RD8/32MER | 32GB | 22 | E4 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 2018 | Rambus | B0 |
| Kingston | KSM32RD8/32MEM | 32GB | 22 | E4 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 2018 | Montage | H1 |
| Kingston | KSM32RD8/32MEI | 32GB | 22 | E4 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 2018 | IDT | C1 |
| Kingston | KSM32RS8/16MER | 16GB | 22 | D1 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 2020 | Rambus | B0 |
| Kingston | KSM32RD4/64MER | 64GB | 22 | B4 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 2024 | Rambus | B0 |
| Kingston | KSM32RD4/64MEM | 64GB | 22 | B4 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 2024 | Montage | H1 |
| Kingston | KSM32RD4/64MEI | 64GB | 22 | B4 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 2024 | IDT | C1 |
| Kingston | KSM32RS8/16MEM | 16GB | 22 | D1 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 2018 | Montage | H1 |
| Kingston | KSM32RS8/16MEI | 16GB | 22 | D1 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 2018 | IDT | C1 |
| Kingston | KSM32RS4/32MER | 32GB | 23 | C3 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 2024 | Rambus | B0 |
| Kingston | KSM32RS4/32MEM | 32GB | 24 | C3 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 2024 | Montage | H1 |
| Kingston | KSM32RS4/32MEI | 32GB | 25 | C3 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 2018 | IDT | C1 |
| Kingston | KSM32RD8/32HAR | 32GB | 22 | E4 | SK hynix | H5ANAG8NAJR-XNC | 16Gb | x8 | 2026 | Rambus | B0 |
| Kingston | KSM32RD8/32HAM | 32GB | 22 | E4 | SK hynix | H5ANAG8NAJR-XNC | 16Gb | x8 | 2026 | Montage | H1 |
| Kingston | KSM32RD8/32HAI | 32GB | 22 | E4 | SK hynix | H5ANAG8NAJR-XNC | 16Gb | x8 | 2026 | IDT | C1 |
| Kingston | KSM32RS8/16HAR | 16GB | 22 | D1 | SK hynix | H5ANAG8NAJR-XNC | 16Gb | x8 | 2026 | Rambus | B0 |
| Kingston | KSM32RS8/16HAM | 16GB | 22 | D1 | SK hynix | H5ANAG8NAJR-XNC | 16Gb | x8 | 2026 | Montage | H1 |
| Kingston | KSM32RS8/16HAI | 16GB | 22 | D1 | SK hynix | H5ANAG8NAJR-XNC | 16Gb | x8 | 2026 | IDT | C1 |
| Kingston | KSM32RD4/64HAR | 64GB | 22 | B4 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 2010 | Rambus | B0 |
| Kingston | KSM32RD4/64HAM | 64GB | 22 | B4 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 2010 | Montage | H1 |
| Kingston | KSM32RD4/64HAI | 64GB | 22 | B4 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 2010 | IDT | C1 |
| Kingston | KSM32RS4/32HAR | 32GB | 22 | C3 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 2010 | Rambus | B0 |
| Kingston | KSM32RS4/32HAM | 32GB | 22 | C3 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 2010 | Montage | H1 |
| Kingston | KSM32RS4/32HAI | 32GB | 22 | C3 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 2010 | IDT | C1 |
| Kingston | KSM32RD8/16HCR | 16GB | 22 | E4 | SK hynix | H5AN8G8NCJR-XNC | 8Gb | x8 | 1950 | Rambus | B0 |
| Kingston | KSM32RD8/16HCI | 16GB | 22 | E4 | SK hynix | H5AN8G8NCJR-XNC | 8Gb | x8 | 1950 | IDT | C1 |
| Kingston | KSM32RD4/32HDR | 32GB | 22 | B2 | SK hynix | H5AN8G4NDJR-XNC | 8Gb | x4 | 2009 | Rambus | B0 |
| Kingston | KSM32RD4/32HDM | 32GB | 22 | B2 | SK hynix | H5AN8G4NDJR-XNC | 8Gb | x4 | 2009 | Montage | H1 |
| Kingston | KSM32RD4/32HDI | 32GB | 22 | B2 | SK hynix | H5AN8G4NDJR-XNC | 8Gb | x4 | 2009 | IDT | C1 |
| Kingston | KSM32RS8/16HCI | 16GB | 22 | D1 | SK hynix | H5ANAG8NCJR-XNC | 16Gb | x8 | 2101 | IDT | C1 |
| Kingston | KSM32RS8/16HCR | 16GB | 22 | D1 | SK hynix | H5ANAG8NCJR-XNC | 16Gb | x8 | 2101 | Rambus | B0 |
| Kingston | KSM32RD8/32HCI | 32GB | 22 | E4 | SK hynix | H5ANAG8NCJR-XNC | 16Gb | x8 | 2101 | IDT | C1 |
| Kingston | KSM32RD8/32HCM | 32GB | 22 | E4 | SK hynix | H5ANAG8NCJR-XNC | 16Gb | x8 | 2101 | Montage | H1 |
| Kingston | KSM32RD8/32HCR | 32GB | 22 | E4 | SK hynix | H5ANAG8NCJR-XNC | 16Gb | x8 | 2101 | Rambus | B0 |
| Kingston | KSM32RS4/32HCI | 32GB | 22 | C3 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2101 | IDT | C1 |
| Kingston | KSM32RS4/32HCR | 32GB | 22 | C3 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2101 | Rambus | B0 |
| Kingston | KSM32RD4/64HCI | 64GB | 22 | B4 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2101 | IDT | C1 |
| Kingston | KSM32RD4/64HCM | 64GB | 22 | B4 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2101 | Montage | H1 |

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| DDR4 RDIMM tested in the following conditions: 3200 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channels 2933 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channel | | | | | | | | | | | |
|---|-----------------------|------|----|----------|---------------|-------------------|-------------|-------|-----------|-----------------|--------------|
| | | DIMM | | | DRAM | | | | | Register | |
| DIMM Supplier | DIMM Part Number | Size | CL | Raw Card | DRAM Supplier | DRAM Part Number | Die Density | Width | Date Code | Register Vendor | Register Rev |
| Kingston | KSM32RD4/64HCR | 64GB | 22 | B4 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2101 | Rambus | B0 |
| Micron Technology | MTA18ASF2G72PZ-3G2E2 | 16GB | 22 | C2 | Micron | MT40A2G4SA-062E:E | 8Gb | x4 | 2028 | Rambus | B0 |
| Micron Technology | MTA18ASF2G72PZ-3G2E2 | 16GB | 22 | C2 | Micron | MT40A2G4SA-062E:E | 8Gb | x4 | 2028 | Montage | H1 |
| Micron Technology | MTA18ASF2G72PZ-3G2E2 | 16GB | 22 | C2 | Micron | MT40A2G4SA-062E:E | 8Gb | x4 | 2028 | IDT | C1 |
| Micron Technology | MTA9ASF1G72PZ-3G2E2 | 8GB | 22 | D1 | Micron | MT40A1G8SA-062E:E | 8Gb | x8 | 2028 | Rambus | B0 |
| Micron Technology | MTA9ASF1G72PZ-3G2E2 | 8GB | 22 | D1 | Micron | MT40A1G8SA-062E:E | 8Gb | x8 | 2028 | Montage | H1 |
| Micron Technology | MTA9ASF1G72PZ-3G2E2 | 8GB | 22 | D1 | Micron | MT40A1G8SA-062E:E | 8Gb | x8 | 2028 | IDT | C1 |
| Micron Technology | MTA36ASF4G72PZ-3G2E7 | 32GB | 22 | B2 | Micron | MT40A2G4SA-062E:E | 8Gb | x4 | 2028 | Rambus | B0 |
| Micron Technology | MTA36ASF4G72PZ-3G2E7 | 32GB | 22 | B2 | Micron | MT40A2G4SA-062E:E | 8Gb | x4 | 2028 | Montage | H1 |
| Micron Technology | MTA36ASF4G72PZ-3G2E7 | 32GB | 22 | B2 | Micron | MT40A2G4SA-062E:E | 8Gb | x4 | 2105 | IDT | C1 |
| Micron Technology | MTA18ASF2G72PDZ-3G2E1 | 16GB | 22 | E2 | Micron | MT40A1G8SA-062E:E | 8Gb | x8 | 2028 | Rambus | B0 |
| Micron Technology | MTA18ASF2G72PDZ-3G2E1 | 16GB | 22 | E2 | Micron | MT40A1G8SA-062E:E | 8Gb | x8 | 2028 | Montage | H1 |
| Micron Technology | MTA18ASF2G72PDZ-3G2E1 | 16GB | 22 | E2 | Micron | MT40A1G8SA-062E:E | 8Gb | x8 | 2028 | IDT | C1 |
| Micron Technology | MTA36ASF4G72PZ-3G2J3 | 32GB | 22 | B2 | Micron | MT40A2G4SA-062E:J | 8Gb | x4 | 1918 | Rambus | B0 |
| Micron Technology | MTA36ASF4G72PZ-3G2J3 | 32GB | 22 | B2 | Micron | MT40A2G4SA-062E:J | 8Gb | x4 | 1918 | Montage | H1 |
| Micron Technology | MTA36ASF4G72PZ-3G2J3 | 32GB | 22 | B2 | Micron | MT40A2G4SA-062E:J | 8Gb | x4 | 1918 | IDT | C1 |
| Micron Technology | MTA18ASF2G72PZ-3G2J3 | 16GB | 22 | C2 | Micron | MT40A2G4SA-062E:J | 8Gb | x4 | 1918 | Rambus | B0 |
| Micron Technology | MTA18ASF2G72PZ-3G2J3 | 16GB | 22 | C2 | Micron | MT40A2G4SA-062E:J | 8Gb | x4 | 1918 | Montage | H1 |
| Micron Technology | MTA18ASF2G72PZ-3G2J3 | 16GB | 22 | C2 | Micron | MT40A2G4SA-062E:J | 8Gb | x4 | 1918 | IDT | C1 |
| Micron Technology | MTA18ASF2G72PDZ-3G2J3 | 16GB | 22 | E2 | Micron | MT40A1G8SA-062E:J | 8Gb | x8 | 1918 | Rambus | B0 |
| Micron Technology | MTA18ASF2G72PDZ-3G2J3 | 16GB | 22 | E2 | Micron | MT40A1G8SA-062E:J | 8Gb | x8 | 1918 | Montage | H1 |
| Micron Technology | MTA18ASF2G72PDZ-3G2J3 | 16GB | 22 | E2 | Micron | MT40A1G8SA-062E:J | 8Gb | x8 | 1918 | IDT | C1 |
| Micron Technology | MTA9ASF1G72PZ-3G2J3 | 8GB | 22 | D1 | Micron | MT40A1G8SA-062E:J | 8Gb | x8 | 1918 | Rambus | B0 |
| Micron Technology | MTA9ASF1G72PZ-3G2J3 | 8GB | 22 | D1 | Micron | MT40A1G8SA-062E:J | 8Gb | x8 | 1918 | Montage | H1 |
| Micron Technology | MTA9ASF1G72PZ-3G2J3 | 8GB | 22 | D1 | Micron | MT40A1G8SA-062E:J | 8Gb | x8 | 1918 | IDT | C1 |
| Micron Technology | MTA36ASF8G72PZ-3G2E1 | 64GB | 22 | B4 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 1938 | Rambus | B0 |
| Micron Technology | MTA36ASF8G72PZ-3G2E1 | 64GB | 22 | B4 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 1938 | IDT | C1 |
| Micron Technology | MTA18ASF4G72PZ-3G2E1 | 32GB | 22 | C2 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 1940 | Rambus | B0 |
| Micron Technology | MTA18ASF4G72PZ-3G2E1 | 32GB | 22 | E4 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 1940 | Rambus | B0 |
| Micron Technology | MTA9ASF2G72PZ-3G2E1 | 16GB | 22 | D1 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 1940 | Rambus | B0 |
| Micron Technology | MTA36ASF8G72PZ-3G2E1 | 64GB | 22 | B4 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 1938 | Montage | H1 |
| Micron Technology | MTA18ASF4G72PZ-3G2E1 | 32GB | 22 | C2 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 1942 | Montage | H1 |
| Micron Technology | MTA18ASF4G72PZ-3G2E1 | 32GB | 22 | C2 | Micron | MT40A4G4JC-062E:E | 16Gb | x4 | 1940 | IDT | C1 |
| Micron Technology | MTA18ASF4G72PDZ-3G2E1 | 32GB | 22 | E4 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 1938 | Montage | H1 |
| Micron Technology | MTA18ASF4G72PDZ-3G2E1 | 32GB | 22 | E4 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 1938 | IDT | C1 |
| Micron Technology | MTA18ASF4G72PDZ-3G2E1 | 32GB | 22 | E4 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 1940 | Rambus | B0 |
| Micron Technology | MTA9ASF2G72PZ-3G2E1 | 16GB | 22 | D1 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 1940 | Montage | H1 |
| Micron Technology | MTA9ASF2G72PZ-3G2E1 | 16GB | 22 | D1 | Micron | MT40A2G8JC-062E:E | 16Gb | x8 | 1940 | IDT | C1 |

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| DDR4 RDIMM tested in the following conditions: 3200 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channels 2933 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channel | | | | | | | | | | | |
|---|-----------------------|------|----|----------|---------------|-------------------|-------------|-------|-----------|-----------------|--------------|
| DIMM | | | | | DRAM | | | | | Register | |
| DIMM Supplier | DIMM Part Number | Size | CL | Raw Card | DRAM Supplier | DRAM Part Number | Die Density | Width | Date Code | Register Vendor | Register Rev |
| Micron Technology | MTA36ASF8G72PZ-3G2B2 | 64GB | 22 | B3 | Micron | MT40A4G4VA-062E:B | 16Gb | x4 | 1918 | Rambus | B0 |
| Micron Technology | MTA36ASF8G72PZ-3G2B2 | 64GB | 22 | B3 | Micron | MT40A4G4VA-062E:B | 16Gb | x4 | 1918 | IDT | C1 |
| Micron Technology | MTA36ASF8G72PZ-3G2B2 | 64GB | 22 | B3 | Micron | MT40A4G4VA-062E:B | 16Gb | x4 | 1918 | Montage | H1 |
| Micron Technology | MTA18ASF4G72PZ-3G2B1 | 32GB | 22 | C3 | Micron | MT40A4G4VA-062E:B | 16Gb | x4 | 1918 | Rambus | B0 |
| Micron Technology | MTA18ASF4G72PZ-3G2B1 | 32GB | 22 | C3 | Micron | MT40A4G4VA-062E:B | 16Gb | x4 | 1918 | Montage | H1 |
| Micron Technology | MTA18ASF4G72PZ-3G2B1 | 32GB | 22 | C3 | Micron | MT40A4G4VA-062E:B | 16Gb | x4 | 1918 | IDT | C1 |
| Micron Technology | MTA18ASF4G72PDZ-3G2B1 | 32GB | 22 | E3 | Micron | MT40A2G8VA-062E:B | 16Gb | x8 | 1918 | Rambus | B0 |
| Micron Technology | MTA18ASF4G72PDZ-3G2B1 | 32GB | 22 | E3 | Micron | MT40A2G8VA-062E:B | 16Gb | x8 | 1918 | Montage | H1 |
| Micron Technology | MTA18ASF4G72PDZ-3G2B1 | 32GB | 22 | E3 | Micron | MT40A2G8VA-062E:B | 16Gb | x8 | 1918 | IDT | C1 |
| Micron Technology | MTA9ASF2G72PZ-3G2B1 | 16GB | 22 | D1 | Micron | MT40A2G8VA-062E:B | 16Gb | x8 | 1918 | Rambus | B0 |
| Micron Technology | MTA9ASF2G72PZ-3G2B1 | 16GB | 22 | D1 | Micron | MT40A2G8VA-062E:B | 16Gb | x8 | 1918 | Montage | H1 |
| Micron Technology | MTA9ASF2G72PZ-3G2B1 | 16GB | 22 | D1 | Micron | MT40A2G8VA-062E:B | 16Gb | x8 | 1918 | IDT | C1 |
| Micron Technology | MTA18ASF4G72PDZ-3G2B2 | 32GB | 22 | E4 | Micron | MT40A2G8VA-062E:B | 16Gb | x8 | 1944 | Rambus | B0 |
| Micron Technology | MTA18ASF4G72PDZ-3G2B2 | 32GB | 22 | E4 | Micron | MT40A2G8VA-062E:B | 16Gb | x8 | 1936 | Montage | H1 |
| Micron Technology | MTA18ASF4G72PDZ-3G2B2 | 32GB | 22 | E4 | Micron | MT40A2G8VA-062E:B | 16Gb | x8 | 1938 | IDT | C1 |
| Nanya Technology | NT16GA72D8PFX3P-JR | 16GB | 22 | E2 | Nanya | NT5AD1024M8F3-JR | 8Gb | x8 | 2040 | Montage | H1 |
| Nanya Technology | NT16GA72D8PFX3K-JR | 16GB | 22 | E2 | Nanya | NT5AD1024M8F3-JR | 8Gb | x8 | 2040 | IDT | C1 |
| Nanya Technology | NT32GA72D4NFX3P-JR | 32GB | 22 | B2 | Nanya | NT5AD2048M4F3-JR | 8Gb | x4 | 2041 | Montage | H1 |
| Nanya Technology | NT32GA72D4NFX3K-JR | 32GB | 22 | B2 | Nanya | NT5AD2048M4F3-JR | 8Gb | x4 | 2041 | IDT | C1 |
| Nanya Technology | NT16GA72D4PFX3P-JR | 16GB | 22 | C2 | Nanya | NT5AD2048M4F3-JR | 8Gb | x4 | 2041 | Montage | H1 |
| Nanya Technology | NT16GA72D4PFX3K-JR | 16GB | 22 | C2 | Nanya | NT5AD2048M4F3-JR | 8Gb | x4 | 2041 | IDT | C1 |
| Samsung | M393A1K43DB2-CWE | 8GB | 22 | D1 | Samsung | K4A8G085WD-BCWE | 8Gb | x8 | 1950 | Rambus | B0 |
| Samsung | M393A1K43DB2-CWE | 8GB | 22 | D1 | Samsung | K4A8G085WD-BCWE | 8Gb | x8 | 1950 | Montage | H1 |
| Samsung | M393A1K43DB2-CWE | 8GB | 22 | D1 | Samsung | K4A8G085WD-BCWE | 8Gb | x8 | 1950 | IDT | C1 |
| Samsung | M393A4K40DB3-CWE | 32GB | 22 | B2 | Samsung | K4A8G045WD-BCWE | 8Gb | x4 | 1950 | Rambus | B0 |
| Samsung | M393A4K40DB3-CWE | 32GB | 22 | B2 | Samsung | K4A8G045WD-BCWE | 8Gb | x4 | 1950 | Montage | H1 |
| Samsung | M393A4K40DB3-CWE | 32GB | 22 | B2 | Samsung | K4A8G045WD-BCWE | 8Gb | x4 | 1950 | IDT | C1 |
| Samsung | M393A2K40DB3-CWE | 16GB | 22 | C2 | Samsung | K4A8G045WD-BCWE | 8Gb | x4 | 1950 | Rambus | B0 |
| Samsung | M393A2K40DB3-CWE | 16GB | 22 | C2 | Samsung | K4A8G045WD-BCWE | 8Gb | x4 | 1950 | Montage | H1 |
| Samsung | M393A2K40DB3-CWE | 16GB | 22 | C2 | Samsung | K4A8G045WD-BCWE | 8Gb | x4 | 1950 | IDT | C1 |
| Samsung | M393A2K43DB3-CWE | 16GB | 22 | E2 | Samsung | K4A8G085WD-BCWE | 8Gb | x8 | 1950 | Rambus | B0 |
| Samsung | M393A2K43DB3-CWE | 16GB | 22 | E2 | Samsung | K4A8G085WD-BCWE | 8Gb | x8 | 1950 | Montage | H1 |
| Samsung | M393A2K43DB3-CWE | 16GB | 22 | E2 | Samsung | K4A8G085WD-BCWE | 8Gb | x8 | 1950 | IDT | C1 |
| Samsung | M393A4G40AB3-CWE | 32GB | 22 | C3 | Samsung | K4AAG045WA-BCWE | 16Gb | x4 | 1925 | Rambus | B0 |
| Samsung | M393A4G40AB3-CWE | 32GB | 22 | C3 | Samsung | K4AAG045WA-BCWE | 16Gb | x4 | 1925 | Montage | H1 |
| Samsung | M393A4G40AB3-CWE | 32GB | 22 | C3 | Samsung | K4AAG045WA-BCWE | 16Gb | x4 | 1925 | IDT | C1 |
| Samsung | M393A8G40AB2-CWE | 64GB | 22 | A2 | Samsung | K4AAG045WA-BCWE | 16Gb | x4 | 1925 | Rambus | B0 |
| Samsung | M393A8G40AB2-CWE | 64GB | 22 | A2 | Samsung | K4AAG045WA-BCWE | 16Gb | x4 | 1925 | IDT | C1 |

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| DDR4 RDIMM tested in the following conditions: 3200 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channels 2933 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channel | | | | | | | | | | | |
|---|--------------------|------|----|----------|---------------|------------------|-------------|-------|-----------|-----------------|--------------|
| DIMM | | | | | DRAM | | | | | Register | |
| DIMM Supplier | DIMM Part Number | Size | CL | Raw Card | DRAM Supplier | DRAM Part Number | Die Density | Width | Date Code | Register Vendor | Register Rev |
| Samsung | M393A8G40AB2-CWE | 64GB | 22 | A2 | Samsung | K4AAG045WA-BCWE | 16Gb | x4 | 1925 | Montage | H1 |
| Samsung | M393A4G43AB3-CWE | 32GB | 22 | E3 | Samsung | K4AAG085WA-BCWE | 16Gb | x8 | 1928 | Rambus | B0 |
| Samsung | M393A4G43AB3-CWE | 32GB | 22 | E3 | Samsung | K4AAG085WA-BCWE | 16Gb | x8 | 1928 | Montage | H1 |
| Samsung | M393A4G43AB3-CWE | 32GB | 22 | E3 | Samsung | K4AAG085WA-BCWE | 16Gb | x8 | 1928 | IDT | C1 |
| Samsung | M393A2K40EB3-CWE | 16GB | 22 | C2 | Samsung | K4A8G045WE-BCWE | 8Gb | x4 | 2016 | Rambus | B0 |
| Samsung | M393A2K40EB3-CWE | 16GB | 22 | C2 | Samsung | K4A8G045WE-BCWE | 8Gb | x4 | 2016 | Montage | H1 |
| Samsung | M393A2K40EB3-CWE | 16GB | 22 | C2 | Samsung | K4A8G045WE-BCWE | 8Gb | x4 | 2016 | IDT | C1 |
| Samsung | M393A2K43EB3-CWE | 16GB | 22 | E2 | Samsung | K4A8G085WE-BCWE | 8Gb | x8 | 2016 | Rambus | B0 |
| Samsung | M393A2K43EB3-CWE | 16GB | 22 | E2 | Samsung | K4A8G085WE-BCWE | 8Gb | x8 | 2016 | Montage | H1 |
| Samsung | M393A2K43EB3-CWE | 16GB | 22 | E2 | Samsung | K4A8G085WE-BCWE | 8Gb | x8 | 2016 | IDT | C1 |
| Samsung | M393A4K40EB3-CWE | 32GB | 22 | B2 | Samsung | K4A8G045WE-BCWE | 8Gb | x4 | 2037 | Rambus | B0 |
| Samsung | M393A4K40EB3-CWE | 32GB | 22 | B2 | Samsung | K4A8G045WE-BCWE | 8Gb | x4 | 2016 | Montage | H1 |
| Samsung | M393A4K40EB3-CWE | 32GB | 22 | B2 | Samsung | K4A8G045WE-BCWE | 8Gb | x4 | 2016 | IDT | C1 |
| Samsung | M393A4G43BB4-CWE | 32GB | 22 | E4 | Samsung | K4AAG045WB-BCWE | 16Gb | x8 | 2043 | IDT | C1 |
| Samsung | M393A4G43BB4-CWE | 32GB | 22 | E4 | Samsung | K4AAG045WB-BCWE | 16Gb | x8 | 2043 | Montage | H1 |
| Samsung | M393A4G43BB4-CWE | 32GB | 22 | E4 | Samsung | K4AAG045WB-BCWE | 16Gb | x8 | 2043 | Rambus | B0 |
| Samsung | M393A8G40BB4-CWE | 64GB | 22 | B4 | Samsung | K4AAG045WB-BCWE | 16Gb | x4 | 2034 | IDT | C1 |
| Samsung | M393A8G40BB4-CWE | 64GB | 22 | B4 | Samsung | K4AAG045WB-BCWE | 16Gb | x4 | 2034 | Montage | H1 |
| Samsung | M393A8G40BB4-CWE | 64GB | 22 | B4 | Samsung | K4AAG045WB-BCWE | 16Gb | x4 | 2034 | Rambus | B0 |
| SK hynix | HMA84GR7CJR4N-XNT8 | 32GB | 22 | B2 | SK hynix | H5AN8G4NCJR-XNC | 8Gb | x4 | 1909 | Rambus | B0 |
| SK hynix | HMA84GR7CJR4N-XNT4 | 32GB | 22 | B2 | SK hynix | H5AN8G4NCJR-XNC | 8Gb | x4 | 1922 | Montage | H1 |
| SK hynix | HMA84GR7CJR4N-XNTG | 32GB | 22 | B2 | SK hynix | H5AN8G4NCJR-XNC | 8Gb | x4 | 1922 | IDT | C1 |
| SK hynix | HMA82GR7CJR4N-XNT8 | 16GB | 22 | C2 | SK hynix | H5AN8G4NCJR-XNC | 8Gb | x4 | 1922 | Rambus | B0 |
| SK hynix | HMA82GR7CJR4N-XNT4 | 16GB | 22 | C2 | SK hynix | H5AN8G4NCJR-XNC | 8Gb | x4 | 1922 | Montage | H1 |
| SK hynix | HMA82GR7CJR4N-XNTG | 16GB | 22 | C2 | SK hynix | H5AN8G4NCJR-XNC | 8Gb | x4 | 1922 | IDT | C1 |
| SK hynix | HMA82GR7CJR8N-XNT8 | 16GB | 22 | E2 | SK hynix | H5AN8G8NCJR-XNC | 8Gb | x8 | 1914 | Rambus | B0 |
| SK hynix | HMA82GR7CJR8N-XNT4 | 16GB | 22 | E2 | SK hynix | H5AN8G8NCJR-XNC | 8Gb | x8 | 1922 | Montage | H1 |
| SK hynix | HMA82GR7CJR8N-XNTG | 16GB | 22 | E2 | SK hynix | H5AN8G8NCJR-XNC | 8Gb | x8 | 1922 | IDT | C1 |
| SK hynix | HMA84GR7DJR4N-XNT8 | 32GB | 22 | B2 | SK hynix | H5AN8G4NDJR-XNC | 8Gb | x4 | 1924 | Rambus | B0 |
| SK hynix | HMA84GR7DJR4N-XNT4 | 32GB | 22 | B2 | SK hynix | H5AN8G4NDJR-XNC | 8Gb | x4 | 1924 | Montage | H1 |
| SK hynix | HMA84GR7DJR4N-XNTG | 32GB | 22 | B2 | SK hynix | H5AN8G4NDJR-XNC | 8Gb | x4 | 1924 | IDT | C1 |
| SK hynix | HMA82GR7DJR4N-XNT8 | 16GB | 22 | C2 | SK hynix | H5AN8G4NDJR-XNC | 8Gb | x4 | 1924 | Rambus | B0 |
| SK hynix | HMA82GR7DJR4N-XNT4 | 16GB | 22 | C2 | SK hynix | H5AN8G4NDJR-XNC | 8Gb | x4 | 1924 | Montage | H1 |
| SK hynix | HMA82GR7DJR4N-XNTG | 16GB | 22 | C2 | SK hynix | H5AN8G4NDJR-XNC | 8Gb | x4 | 1924 | IDT | C1 |
| SK hynix | HMA82GR7DJR8N-XNT8 | 16GB | 22 | E2 | SK hynix | H5AN8G8NDJR-XNC | 8Gb | x8 | 1924 | Rambus | B0 |
| SK hynix | HMA82GR7DJR8N-XNT4 | 16GB | 22 | E2 | SK hynix | H5AN8G8NDJR-XNC | 8Gb | x8 | 1924 | Montage | H1 |
| SK hynix | HMA82GR7DJR8N-XNTG | 16GB | 22 | E2 | SK hynix | H5AN8G8NDJR-XNC | 8Gb | x8 | 1924 | IDT | C1 |

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|---|---------------------|-------|----|----------|---------------|------------------|-------------|-------|-----------|-----------------|--------------|
| DIMM | | | | DRAM | | | | | | Register | |
| DIMM Supplier | DIMM Part Number | Size | CL | Raw Card | DRAM Supplier | DRAM Part Number | Die Density | Width | Date Code | Register Vendor | Register Rev |
| SK hynix | HMAA8GR7AJR4N-XNT8 | 64GB | 22 | B4 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 1927 | Rambus | B0 |
| SK hynix | HMAA8GR7AJR4N-XNTG | 64GB | 22 | B4 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 1927 | IDT | C1 |
| SK hynix | HMAA8GR7AJR4N-XNT4 | 64GB | 22 | B4 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 1927 | Montage | H1 |
| SK hynix | HMAA4GR7AJR4N-XNT8 | 32GB | 22 | C3 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 1927 | Rambus | B0 |
| SK hynix | HMAA4GR7AJR4N-XNT4 | 32GB | 22 | C3 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 1927 | Montage | H1 |
| SK hynix | HMAA4GR7AJR4N-XNTG | 32GB | 22 | C3 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 1927 | IDT | C1 |
| SK hynix | HMAA4GR7AJR8N-XNT8 | 32GB | 22 | E4 | SK hynix | H5ANAG8NAJR-XNC | 16Gb | x8 | 1927 | Rambus | B0 |
| SK hynix | HMAA4GR7AJR8N-XNT4 | 32GB | 22 | E4 | SK hynix | H5ANAG8NAJR-XNC | 16Gb | x8 | 1927 | Montage | H1 |
| SK hynix | HMAA4GR7AJR8N-XNTG | 32GB | 22 | E4 | SK hynix | H5ANAG8NAJR-XNC | 16Gb | x8 | 1927 | IDT | C1 |
| SK hynix | HMAA8GR7CJR4N-XNT8 | 64GB | 22 | B2 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2018 | Rambus | B0 |
| SK hynix | HMAA8GR7CJR4N-XNT4 | 64GB | 22 | B2 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2018 | Montage | H1 |
| SK hynix | HMAA8GR7CJR4N-XNTG | 64GB | 22 | B2 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2018 | IDT | C1 |
| SK hynix | HMAA4GR7CJR4N-XNT8 | 32GB | 22 | C2 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2017 | Rambus | B0 |
| SK hynix | HMAA4GR7CJR4N-XNT4 | 32GB | 22 | C2 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2017 | Montage | H1 |
| SK hynix | HMAA4GR7CJR4N-XNTG | 32GB | 22 | C2 | SK hynix | H5ANAG4NCJR-XNC | 16Gb | x4 | 2017 | IDT | C1 |
| SK hynix | HMAA4GR7CJR8N-XNT8 | 32GB | 22 | E2 | SK hynix | H5ANAG8NCJR-XNC | 16Gb | x8 | 2017 | Rambus | B0 |
| SK hynix | HMAA4GR7CJR8N-XNT4 | 32GB | 22 | E2 | SK hynix | H5ANAG8NCJR-XNC | 16Gb | x8 | 2017 | Montage | H1 |
| SK hynix | HMAA4GR7CJR8N-XNTG | 32GB | 22 | E2 | SK hynix | H5ANAG8NCJR-XNC | 16Gb | x8 | 2017 | IDT | C1 |
| SK hynix | HMABAGR7A2R4N-XST4 | 128GB | 26 | B4 | SK hynix | H5ANBG4TA2R-XSC | 16Gb 3DS | x4 | 1930 | Montage | H1 |
| SK hynix | HMABAGR7A2R4N-XSTG | 128GB | 26 | B4 | SK hynix | H5ANBG4TA2R-XSC | 16Gb 3DS | x4 | 1930 | IDT | C1 |
| SK hynix | HMAT14JXSRB120N | 256GB | 26 | B3 | SK hynix | H5AG64JXSXD042 | 16Gb 3DS | x4 | 2037 | Montage | H1 |
| SK hynix | HMAT14JXSRB122N | 256GB | 26 | B3 | SK hynix | H5AG64JXSXD042 | 16Gb 3DS | x4 | 2037 | IDT | C1 |
| UnilC | SCC32GP13H2F1C-32AA | 16GB | 22 | E4 | SK hynix | H5ANAG8NAJR-XNC | 16Gb | x8 | 2028 | Rambus | B0 |
| UnilC | SCC64GP12H2F1C-32AA | 64GB | 22 | B4 | SK hynix | H5ANAG4NAJR-XNC | 16Gb | x4 | 2009 | Montage | H1 |

Updated April 23, 2021

Approved test labs
The following test labs have the capability of performing system-level testing. For further information, please contact:

Advanced Validation Labs (AVL)
Rhonda_Duda@validationlabs.com
17665B Newhope Street
Fountain Valley, CA 92708
USA